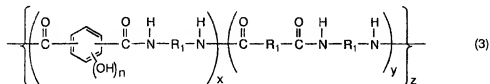


# **AMENDMENTS TO THE CLAIMS**

The following listing of claims replaces all previous claims, and listings of claims, in the application.

Claim 1 (original): A process for producing a surface-adhesive film comprising applying a polyimide precursor solution to a substrate, drying the polyimide precursor solution to prepare a polyimide precursor film, applying an adhesive aid composition containing a phenolic hydroxyl group-containing polyamide and a solvent to the polyimide precursor film, drying the adhesive aid composition, and then imidizing the polyimide precursor by heating at 200°C to 500°C.

Claim 2 (original): The process for producing a surface-adhesive film according to claim 1, wherein the phenolic hydroxyl group-containing polyamide is a polyamide having a repeat structure represented by formula (3):



(wherein R<sub>1</sub> represents a divalent aromatic group and R<sub>1</sub>s in repeating units may be the same or different; n represents an average number of substituents and is a positive number of 1 to 4; and x,

y, and z represent average degrees of polymerization and are positive numbers of 1 to 10, 0 to 20, and 1 to 50, respectively).

Claim 3 (previously presented): The process for producing a surface-adhesive film according to claim 1, wherein the precursor solution is dried at 50°C to 150°C for 5 to 180 minutes, the adhesive aid composition is dried at 50°C to 150°C for 5 to 180 minutes, and the polyimide precursor is heated at 200°C to 500°C for 20 to 300 minutes under a nitrogen stream.

Claim 4 (previously presented): A film produced by the process according to claim 1.

Claim 5 (previously presented): A single-sided copper-clad laminate comprising the film prepared according to claim 4.

Claim 6 (previously presented): A double-sided copper-clad laminate comprising the film prepared according to claim 4.

Claim 7 (previously presented): A flexible printed wiring board comprising the film prepared according to claim 4.

Claim 8 (previously presented): A multilayer printed wiring board comprising the film prepared according to claim 4.

Claim 9 (previously presented): The process for producing a surface-adhesive film according to claim 2, wherein the precursor solution is dried at 50°C to 150°C for 5 to 180 minutes, the adhesive aid composition is dried at 50°C to 150°C for 5 to 180 minutes, and the polyimide precursor is heated at 200°C to 500°C for 20 to 300 minutes under a nitrogen stream.